

LNPTM THERMOCOMPTM COMPOUND LF006E

LF-1006 EM REGION EUROPE

DESCRIPTION

LNP THERMOCOMP LF006E compound is based on Polyetheretherketone (PEEK) resin containing 30% glass fiber. Added features of this grade include: Easy Molding.

GENERAL INFORMATION	
Features	Good Processability, High stiffness/Strength, High temperature resistance, No PFAS intentionally added
Fillers	Glass Fiber
Polymer Types	Polyetheretherketone (PEEK)
Processing Techniques	Injection Molding

INDUSTRY	SUB INDUSTRY
Consumer	Commercial Appliance
Electrical and Electronics	Electronic Components, Mobile Phone - Computer - Tablets
Industrial	Electrical, Material Handling

TYPICAL PROPERTY VALUES

TYPICAL VALUES	UNITS	TEST METHODS
159	MPa	ISO 527
1.9	%	ISO 527
11200	MPa	ISO 527
222	MPa	ISO 178
9500	MPa	ISO 178
40	kJ / m²	ISO 180/1U
9	kJ / m²	ISO 180/1A
>280	°C	ISO 75/Af
1.53	g/cm³	ISO 1183
120 – 150	°C	
4	Hrs	
0.1	%	
380 - 390	°C	
380 – 395	°C	
365 – 375	°C	
350 – 360		
	159 1.9 11200 222 9500 40 9 1.53 1.53 1.20 - 150 4 0.1 380 - 390 380 - 395 365 - 375	159 MPa 1.9 % 11200 MPa 222 MPa 9500 MPa 40 MPa 9 kl/m² 9 kl/m² 9 kl/m² 1.53 g/cm³ 120 – 150 °C 4 Hrs 0.1 % 380 – 390 °C 380 – 395 °C 365 – 375 °C

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CHEMISTRY THAT MATTERS



PROPERTIES	TYPICAL VALUES	UNITS	TEST METHODS
Mold Temperature	140 – 165	°C	
Back Pressure	0.3 – 0.7	MPa	
Screw Speed	60 - 100	rpm	

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.